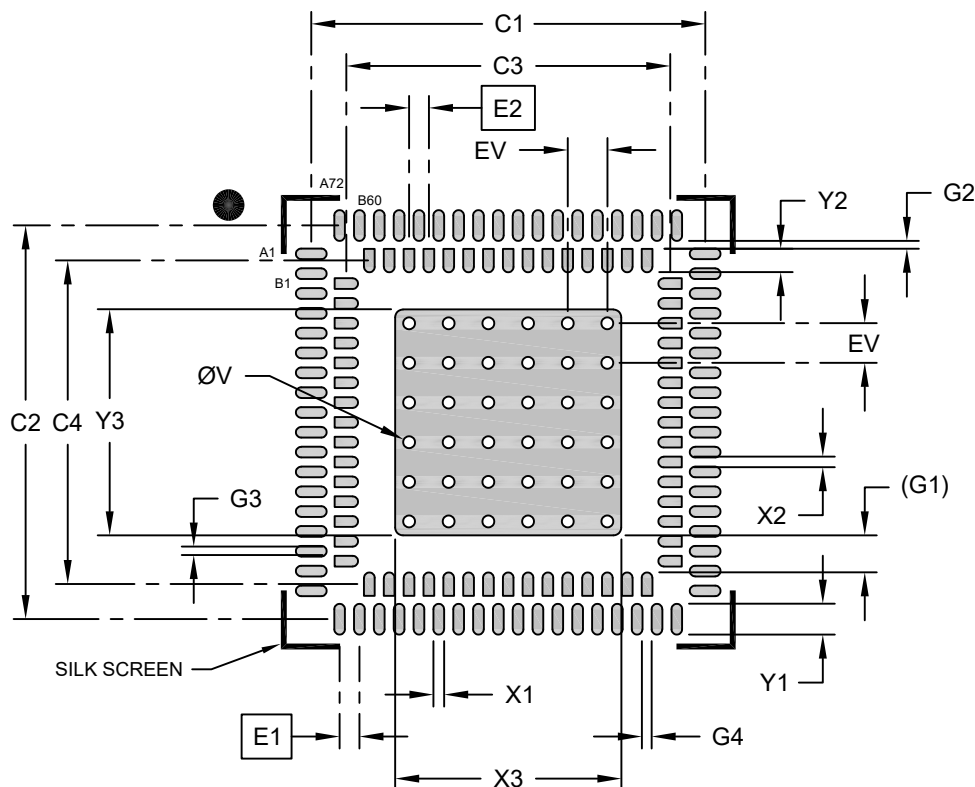


132-Lead Very Thin Plastic Quad Flat, No Lead Package (3WW) - 10x10x0.9 mm Body [VQFN] Dual Row Terminals; Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Outer Contact Pitch	E1	0.50 BSC		
Inner Contact Pitch	E2	0.50 BSC		
Outer Contact Pad Width (X72)	X1			0.30
Inner Contact Pad Width (X60)	X2			0.30
Optional Center Pad Width	X3			5.60
Optional Center Pad Length	Y3			5.60
Outer Contact Pad Spacing	C2		9.93	
Inner Contact Pad Spacing	C3		8.16	

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Inner Contact Pad Spacing	C4		8.16	
Outer Contact Pad Length (X72)	Y1			0.78
Inner Contact Pad Length (X60)	Y2			0.59
Contact Pad to Center Pad (X60)	G1	1.20 REF		
Inner Pad Row to Outer Pad Row	G2	0.20		
Contact Pad to Contact Pad (X68)	G3	0.20		
Contact Pad to Contact Pad (X56)	G4	0.20		
Thermal Via Diameter	V		0.30	
Thermal Via Pitch	EV		1.00	

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process